

# 2			Atty. Docket No.: 1065-US		Serial No.: Unassigned	
			Applicant: Payer, et al.		Group: Unassigned 2839	
			Filing Date: Unassigned		Examiner: Unassigned	

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## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if appropriate
TPA	AA	5,996,221	12/07/1999	Chirovsky, et al.	29	840	TPA
	AB						
	AC						
	AD						
	AE						
	AF						

## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
TPA	AG	98/53355	26 NOV 1998	WO	G02B	7/182		
	AH							
	AI							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

TPA	AJ	Luk, C.F.; Chan, Y.C.; and Hung, K.C., "Development of Gold to Gold Interconnection Flip Chip Bonding for Chip on Suspension Assemblies," 2001 Electronic Components and Technology Conference.
	AK	
	AL	
	AM	
	AN	
	AO	

Examiner T C Patel Date Considered 10/2101

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.